















ESD

TVS

MOS

LDO

Diode

Sensor

DC-DC

# **Product Specification**

Domestic Part Number	BSC034N03LSG
Overseas Part Number	BSC034N03LSG
▶ Equivalent Part Number	BSC034N03LSG





## N-Ch 30V Fast Switching MOSFETs

#### **Features**

- Advanced Trench MOS Technology
- Low Gate Charge
- Low R<sub>DS(ON)</sub>
- 100% EAS Guaranteed
- Green Device Available

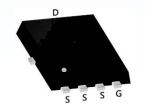
#### **Applications**

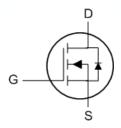
- Power Management in Desktop Computer or DC/DC Converters.
- Isolated DC/DC Converters in Telecom and Industrial.

### **Product Summary**

BVDSS	RDSON	ID
30V	3.8mΩ	75A

## PRPAK5X6 Pin Configuration





#### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage	30	V	
V <sub>G</sub> s	Gate-Source Voltage	±20	V	
I <sub>D</sub> @Tc=25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	75	Α	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	45	А	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	160	Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	144.7	mJ	
I <sub>AS</sub>	Avalanche Current	53.8	А	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	50	W	
T <sub>STG</sub>	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
RθJA	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W
R <sub>0</sub> JC	Thermal Resistance Junction-Case <sup>1</sup>		2.5	°C/W



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## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		3	3.8	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		3.8	5.8	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250uA$	1.2	1.7	2.5	V
l	Drain-Source Leakage Current	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
I <sub>DSS</sub>		$V_{DS}$ =30V , $V_{GS}$ =0V , $T_{J}$ =55°C			5	
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		75		S
Qg	Total Gate Charge (4.5V)	V <sub>DS</sub> =20V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =20A		23.4		
Qgs	Gate-Source Charge			11.4		nC
$Q_{gd}$	Gate-Drain Charge			8.2		
T <sub>d(on)</sub>	Turn-On Delay Time			12.6		
Tr	Rise Time	$V_{DD}$ =15 $V$ , $V_{GS}$ =10 $V$ , $R_{G}$ =1.5 $\Omega$		9.6		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =20A		55		ns
T <sub>f</sub>	Fall Time			5.6		
Ciss	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		2461		
Coss	Output Capacitance			383		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			261		

## **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			40	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V

#### Note:

- 1. The data tested by surface mounted on a 1 inch $^2\,\text{FR-4}$  board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =53.8A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.
- 6. The maximum current rating is package limited.



## **Typical Characteristics**

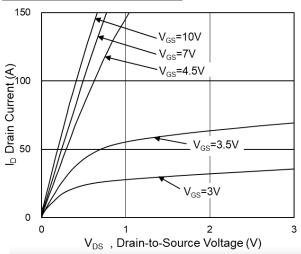


Fig.1 Typical Output Characteristics

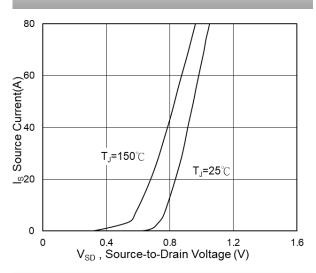


Fig.3 Source Drain Forward Characteristics

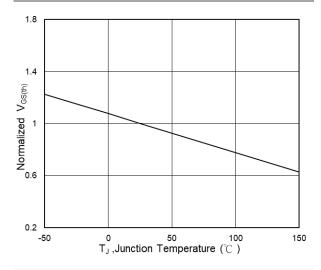


Fig.5 Normalized V<sub>GS(th)</sub> vs T<sub>J</sub>

## N-Ch 30V Fast Switching MOSFETs

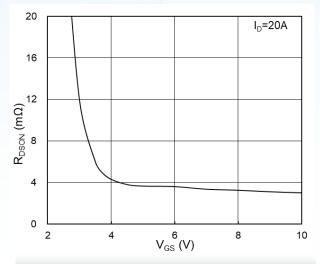


Fig.2 On-Resistance vs G-S Voltage

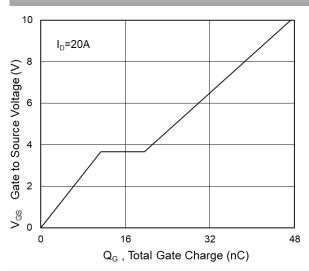


Fig.4 Gate-Charge Characteristics

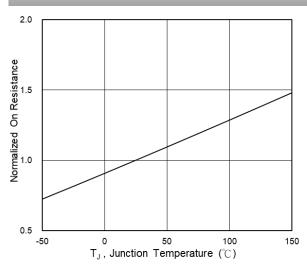
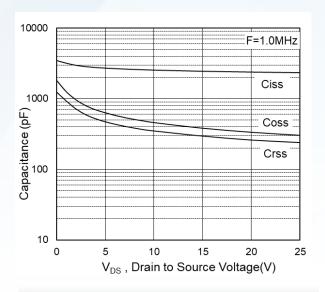


Fig.6 Normalized R<sub>DSON</sub> vs T<sub>J</sub>



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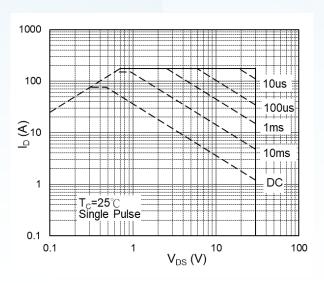


Fig. 8 Safe Operating Area

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Single Pulse

O.001

O.001

O.0001

O.0001

O.0001

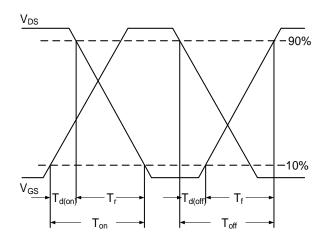
O.0001

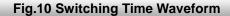
O.0001

O.001

O.00

Fig.9 Normalized Maximum Transient Thermal Impedance





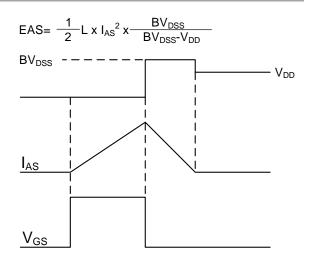


Fig.11 Unclamped Inductive Switching Waveform



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